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TITLE: HEAT-RESISTANT ADHESIVE
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INVENTOR-INFORMATION:

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ABSTRACT:

PURPOSE: To provide the adhesive having a specific

composition, capable of laminating a heat-resistant film to a copper foil at a low temperature to give a laminate containing the adhesive layer having sufficient adhesiveness and excellent flexibility and heat-resistance and, accordingly, suitable for the production of a flexible printed circuit board, etc.

CONSTITUTION: The adhesive contains (A) 100 pts.wt. of a soluble polyimide siloxane produced by reacting an aromatic tetracarboxylic acid component composed mainly of a biphenyltetracarboxylic acid compound (preferably 2,3,3',4'-biphenyltetracarboxylic acid dianhydride) with 10-80mol% of a diaminopolysiloxane of formula (R is bivalent hydrocarbon group; R1 to R4 are lower alkyl or phenyl; n is 3-60) and 20-90mol% of an aromatic diamine (preferably 1,3-diaminodiphenyl ether, etc.), (B) 1-60 pts.wt. of an epoxy.polyoxyalkylene-modified polysiloxane, (C) 15-250 pts.wt. of other epoxy compound, (D) 0.2-20 pts.wt. of an inorganic filler and (E) an epoxy hardener as resin components.